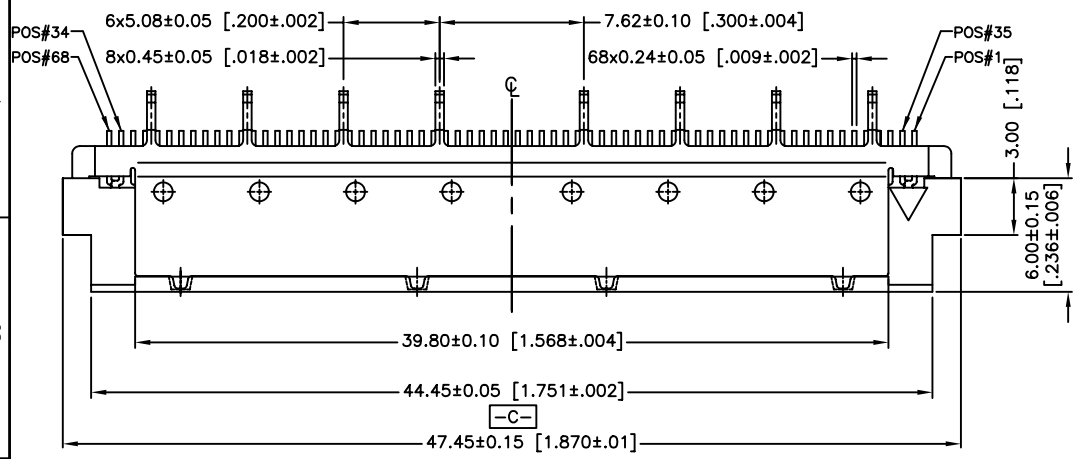
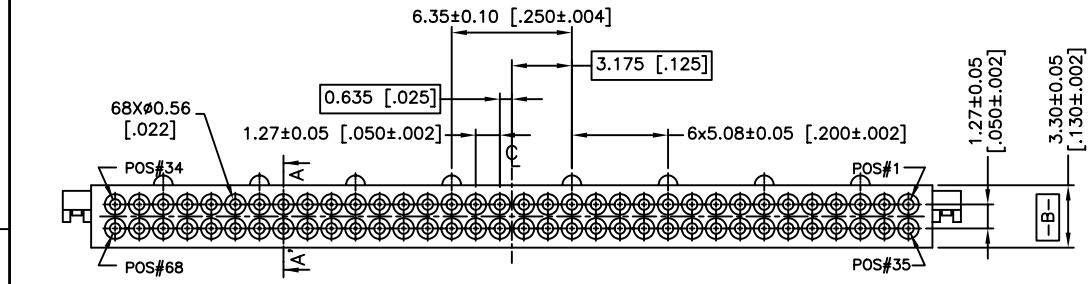
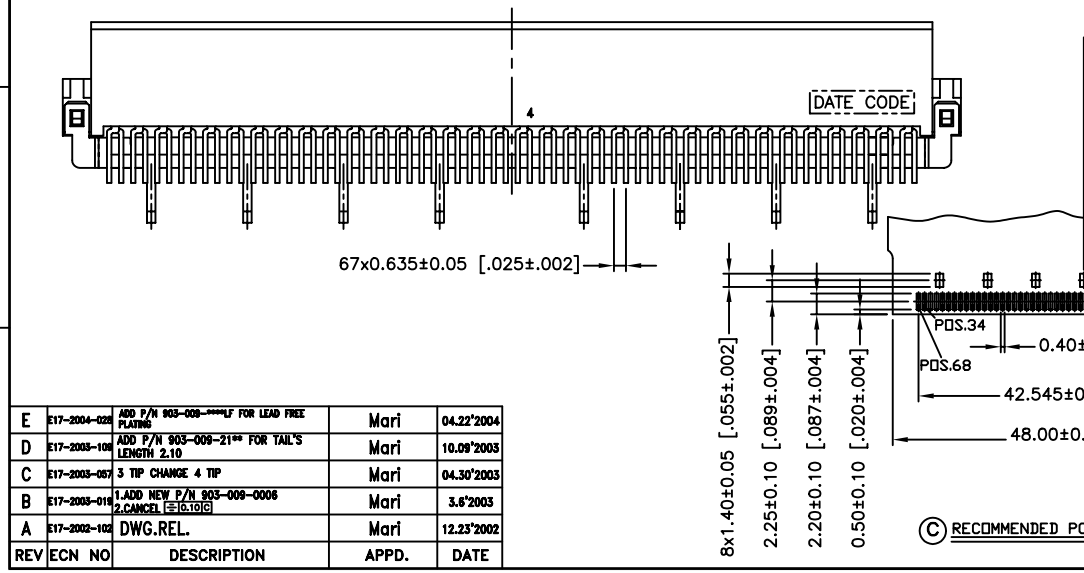
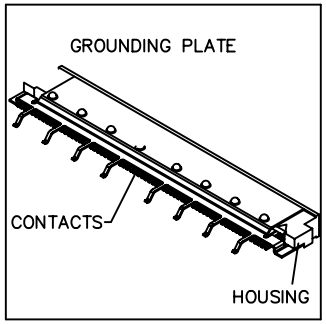






Ⓒ RECOMMENDED PC BOARD DIMENSIONS (1:2)



NOTE:

1. MATERIAL:
   CONTACTS–COPPER ALLOY.
   HOUSING–UL 94V–0 RATED LCP, COLOR: BLACK
   GROUNDING PLATE–COPPER ALLOY.
2. FINISH:
   (E) CONTACTS–15u" MIN GOLD ON MATING AREA OR 5u" MIN. GOLD FLASH ON MATING AREA OVER Pd/Ni 10u"MIN. PLATING AT MATING AREA, 200u" TIN/LEAD OR 120u" TIN PLATING AT SOLDERING TAILS, OVER 50u" MIN. NICKEL UNDERPLATING OVERALL.
   GROUNDING PLATE–5u" MIN GOLD FLASH ON CONTACT AREA, OVER 10u" MIN. Pd/Ni PLATING AT CONTACT AREA, 100u" TIN/LEAD OR TIN PLATING AT SOLDERING TAILS, OVER 50u" MIN. NICKEL UNDERPLATING OVERALL.
3. PROD. NUMBER: SEE 903–009–0000.
   PROD.CODE SPECIFICATION.

9 03 – 0 09 – *0 06 □

- 9: CUSTOMER PROD. SERIES TYPE — PCMCIA SERIES
- 03: CUSTOMER PROD. SERIES TYPE
- 0: CONTACT TYPE & MATING PORT
- 09: POSITION & CONNECTOR STYLE & TERMINATION TYPE
- *0: MODIFICATION (FLOATING NO.)
- 06: CONTACT FINISH — 06 = 15u" GOLD
- □: FOR SPECIAL REQUEST ONLY — □=FOR GENERAL; R =FOR TAPE&REEL; (E) LF=FOR LEAD FREE PLATING

4. RECOMMENDED PC BOARD THICKNESS: 0.56mmMAX.

PROD. NO.	DIM.A +0.18 −0.06 OFFSET	DIM.B±0.05
903–009–2006	+0.60mm	1.92
903–009–1006	+0.30mm	1.65
903–009–0006	0.00mm	1.35

REV	ECN NO	DESCRIPTION	APPD.	DATE
E	E17–2004–026	ADD P/N 903–009–****LF FOR LEAD FREE PLATING	Mari	04.22'2004
D	E17–2003–108	ADD P/N 903–009–21** FOR TAIL'S LENGTH 2.10	Mari	10.09'2003
C	E17–2003–057	3 TIP CHANGE 4 TIP	Mari	04.30'2003
B	E17–2003–019	1.ADD NEW P/N 903–009–0006 2.CANCEL ⌯0.10Ⓒ	Mari	3.6'2003
A	E17–2002–102	DWG.REL.	Mari	12.23'2002

X. ± 0.38[.015]	APPD: Mari Chen 04.22'2004	Mega-Chip Electronics Pte Ltd
.X ± 0.25[.010]		
.XX ± 0.13[.005]	CHKD: Mari Chen 04.22'2004	TITLE: CONN. PCMCIA RECE. G TYPE CARDBUS 68P, 0.00/+0.30/+0.60mm OFFSET
.XXX±		
X° ± 3°	DR: Betty Tai 04.22'2004	DWG NO: 903–009–0000
.X° ±		
UNITS: mm [INCH]	SCALE: NONE	SHEET: 1 OF 3 REV: E